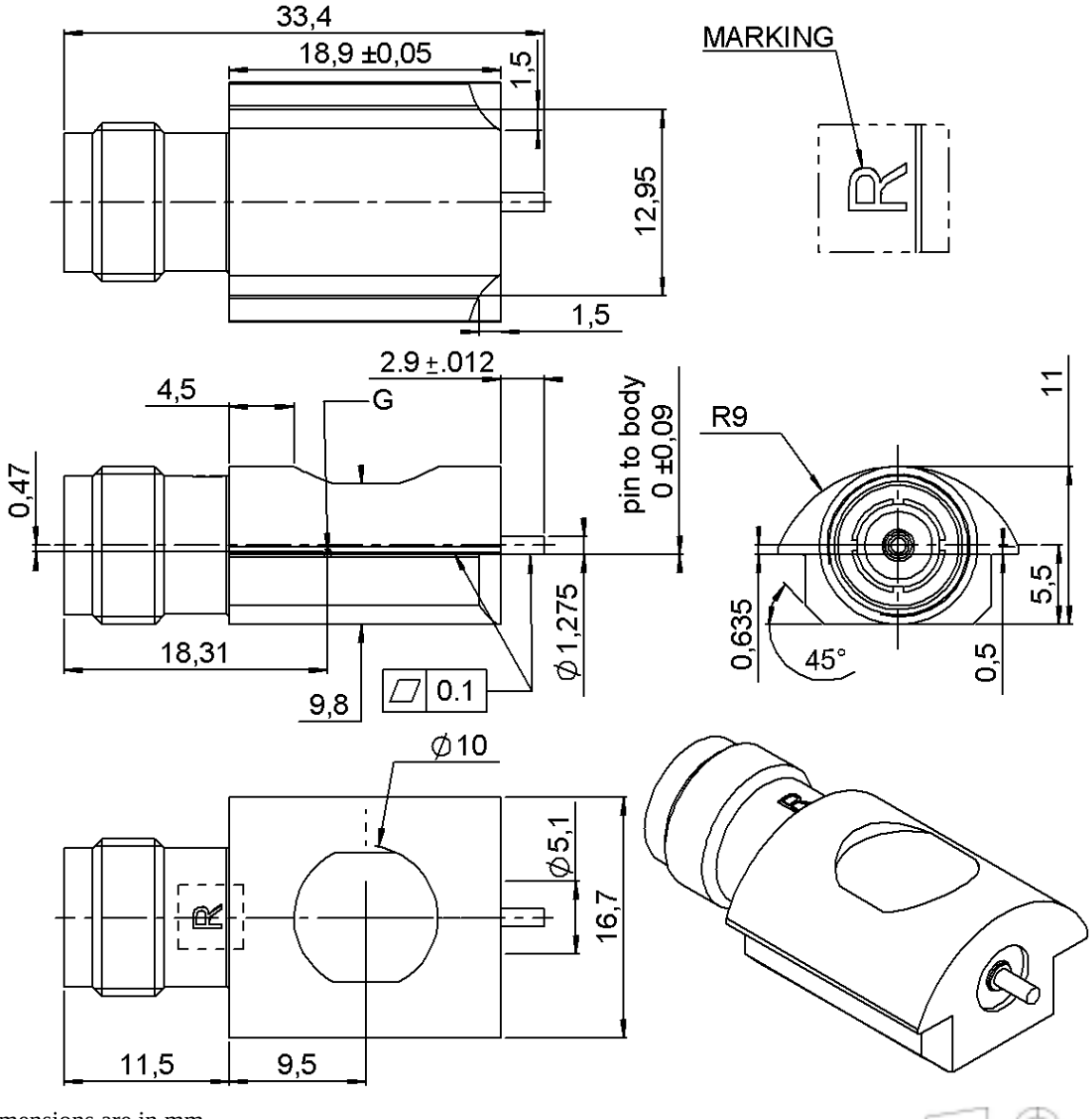
EDGE CARD FEMALE RECEPTACLE

PACKAGING IN REEL 110

R143.424.927

Series : **TNC**



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATINGS (µm)
BODY	**BRASS**	**NPGR**
CENTER CONTACT	**BERYLLIUM COPPER**	**GOLD 1.3 OVER COPPER 2.5**
OUTER CONTACT	-	-
INSULATOR	**PTFE**	
GASKET	-	
OTHERS PARTS	-	**GOLD 0.5 OVER NICKEL 2**
-	-	-
-	-	-

Issue : 0642 E

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PACKAGING

Standard	Unit	Other
110	**'W' option**	**Contact us**

SPECIFICATION

1301-RNT 408 4006 Uen rev. B

ELECTRICAL CHARACTERISTICS

Impedance		**50**	Ω
Frequency		**0-3**	GHz
VSWR	**1.2**	**0,0000**	Maxi
Insertion loss		**0.13**	√F(GHz) dB Maxi
RF leakage	- (	**NA**	- F(GHz)) dB Maxi
Voltage rating		**500**	Veff Maxi
Dielectric withstanding voltage		**1500**	Veff mini
Insulation resistance		**5000**	MΩ mini

ENVIRONMENTAL

Operating temperature	**-40/+85**	° C
Hermetic seal		Atm.cm3/s
Panel leakage	**NA**	

OTHERS CHARACTERISTICS

Assembly instruction

Others :
Intermodulation at 3 rd order at 1900 Mh
2x20 W carrier = TYP.-110 dBm

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	**18**	N mini
Axial force – Opposite end	**18**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating		N.cm
Panel nut		N.cm
Mating life	**500**	Cycles mini
Weight	**20,3800**	g

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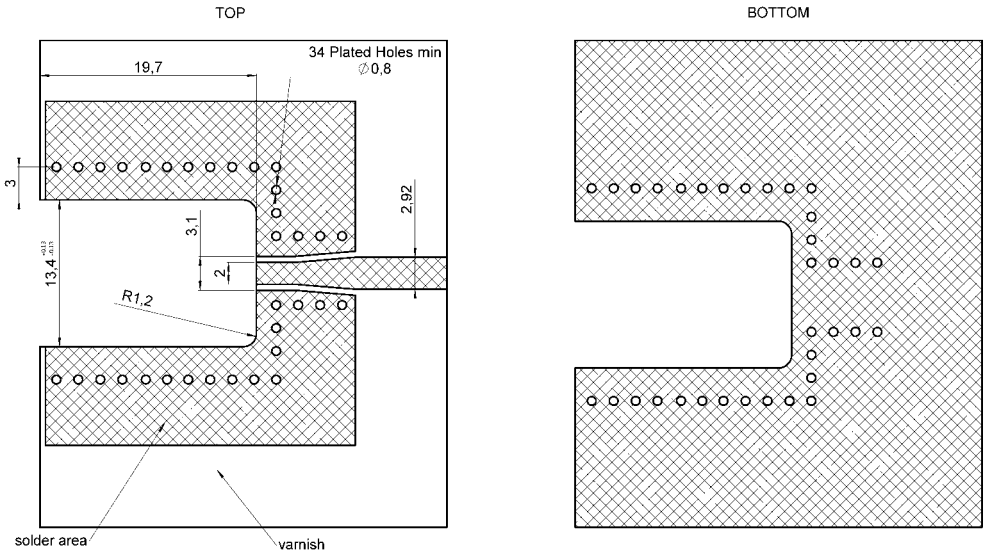
TNC SERIES - INFORMATIONS

Strip line Thickness of PCB : 1.6mm
The material of PCB is FR4 . (Er = 4.6) .



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SOLDER PROCEDURE

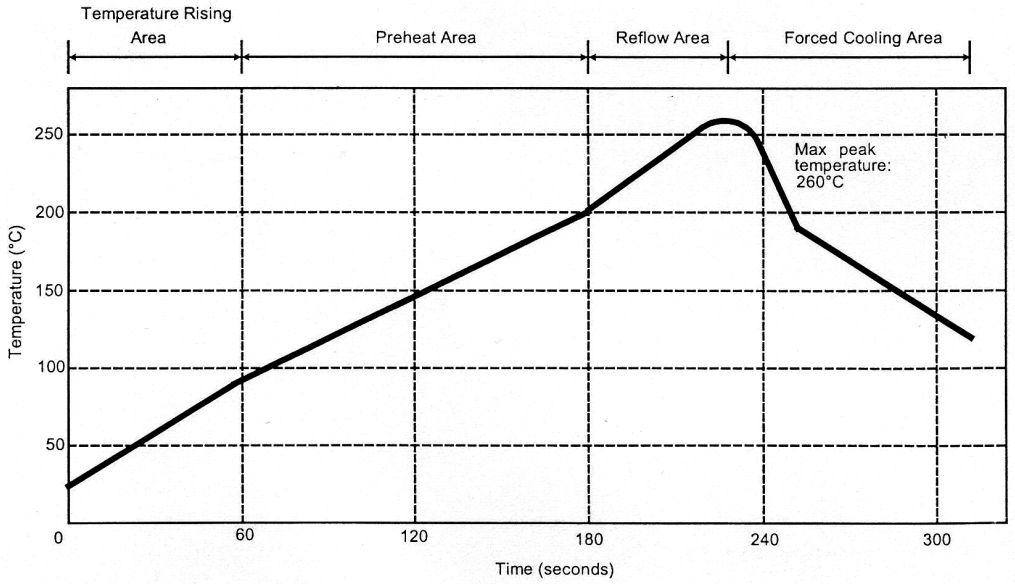
1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
   We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
   Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

3. Soldering by infra-red reflow.
   Below, please find the typical profile to use.

4. Cleaning of printed circuit boards.

5. Checking of solder joints and position of the component by visual inspection.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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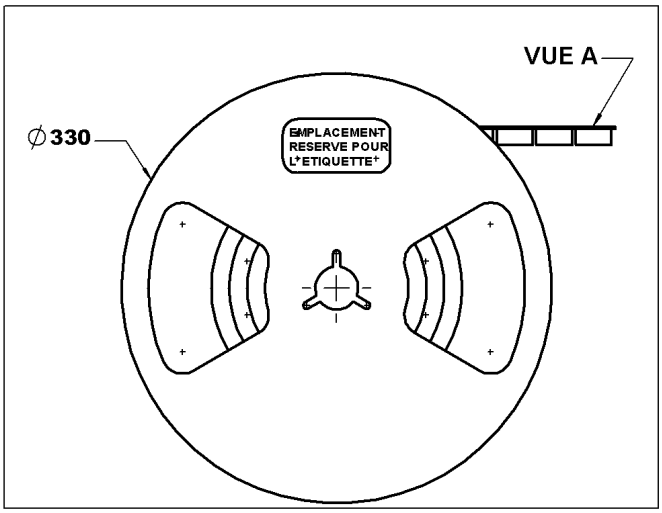

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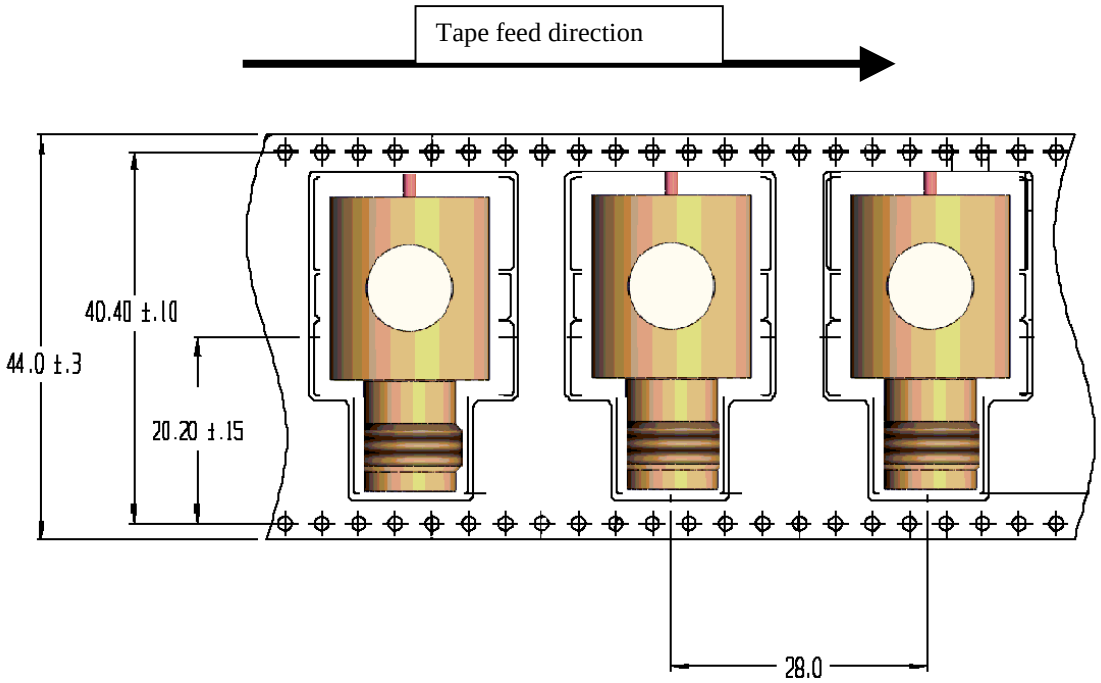

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